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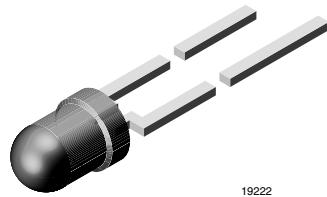
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## High Intensity LED in $\varnothing$ 3 mm Clear Package



19222

### DESCRIPTION

This device has been designed to meet the increasing demand for AlInGaP technology.

It is housed in a 3 mm clear plastic package. The small viewing angle of these devices provides a high brightness.

All packing units are categorized in luminous intensity groups. That allows users to assemble LEDs with uniform appearance.

### PRODUCT GROUP AND PACKAGE DATA

- Product group: LED
- Package: 3 mm
- Product series: standard
- Angle of half intensity:  $\pm 16^\circ$

### FEATURES

- AlInGaP technology
- Standard  $\varnothing$  3 mm (T-1) package
- Small mechanical tolerances
- Suitable for DC and high peak current
- Very small viewing angle
- Very high intensity
- Luminous intensity categorized
- Lead (Pb)-free device

### APPLICATIONS

- Status lights
- OFF/ON indicator
- Background illumination
- Readout lights
- Maintenance lights
- Legend light

### PARTS TABLE

PART	COLOR, LUMINOUS INTENSITY	TECHNOLOGY
TLHK4900	Red, $I_V > 40$	AlInGaP on GaAs

### ABSOLUTE MAXIMUM RATINGS<sup>1)</sup> TLHK4900

PARAMETER	TEST CONDITION	SYMBOL	VALUE	UNIT
Reverse voltage		$V_R$	5	V
DC Forward current	$T_{amb} \leq 60^\circ C$	$I_F$	30	mA
Surge forward current	$t_p \leq 10 \mu s$	$I_{FSM}$	0.1	A
Power dissipation	$T_{amb} \leq 60^\circ C$	$P_V$	80	mW
Junction temperature		$T_j$	100	$^\circ C$
Operating temperature range		$T_{amb}$	- 40 to + 100	$^\circ C$
Storage temperature range		$T_{stg}$	- 55 to + 100	$^\circ C$
Soldering temperature	$t \leq 5 s$ , 2 mm from body	$T_{sd}$	260	$^\circ C$
Thermal resistance junction/ambient		$R_{thJA}$	400	K/W

Note:

<sup>1)</sup>  $T_{amb} = 25^\circ C$ , unless otherwise specified

**OPTICAL AND ELECTRICAL CHARACTERISTICS<sup>1)</sup> TLHK4900, RED**

PARAMETER	TEST CONDITION	SYMBOL	MIN	TYP.	MAX	UNIT
Luminous intensity <sup>2)</sup>	$I_F = 10 \text{ mA}$	$I_V$	40	140		mcd
Dominant wavelength	$I_F = 10 \text{ mA}$	$\lambda_d$		630		nm
Peak wavelength	$I_F = 10 \text{ mA}$	$\lambda_p$		643		nm
Angle of half intensity	$I_F = 10 \text{ mA}$	$\varphi$		$\pm 16$		deg
Forward voltage	$I_F = 20 \text{ mA}$	$V_F$		1.9	2.6	V
Reverse voltage	$I_R = 10 \mu\text{A}$	$V_R$	5			V
Junction capacitance	$V_R = 0, f = 1 \text{ MHz}$	$C_j$		15		pF

Note:

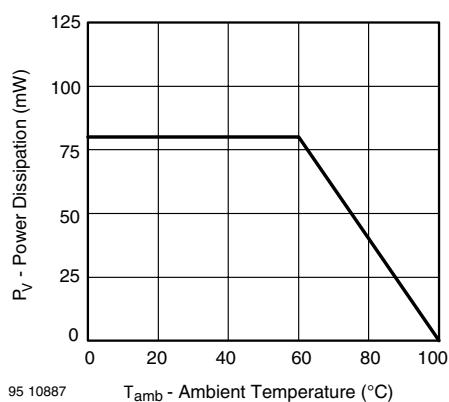
1)  $T_{\text{amb}} = 25 \text{ }^{\circ}\text{C}$ , unless otherwise specified2) in one packing unit  $I_{V\text{min}}/I_{V\text{max}} \leq 0.5$ 
**TYPICAL CHARACTERISTICS**
 $T_{\text{amb}} = 25 \text{ }^{\circ}\text{C}$ , unless otherwise specified

Figure 1. Power Dissipation vs. Ambient Temperature

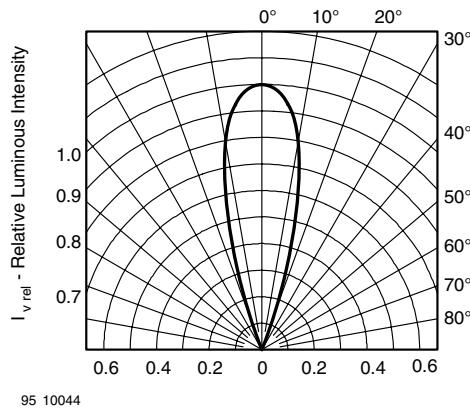


Figure 3. Rel. Luminous Intensity vs. Angular Displacement

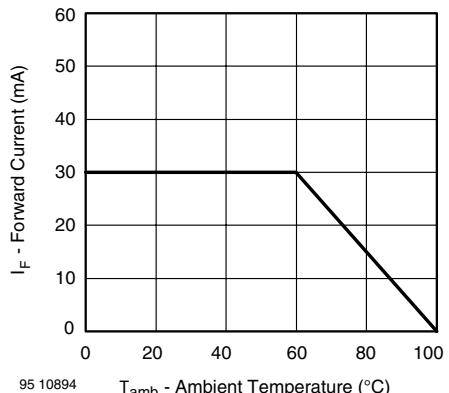


Figure 2. Forward Current vs. Ambient Temperature for InGaN

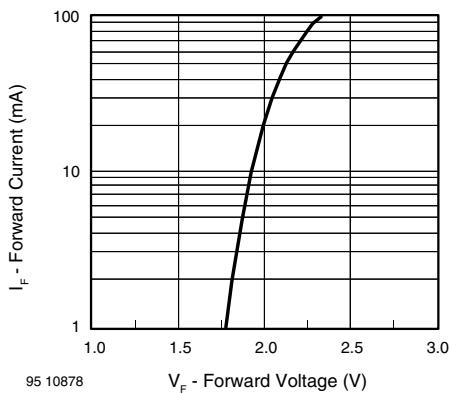
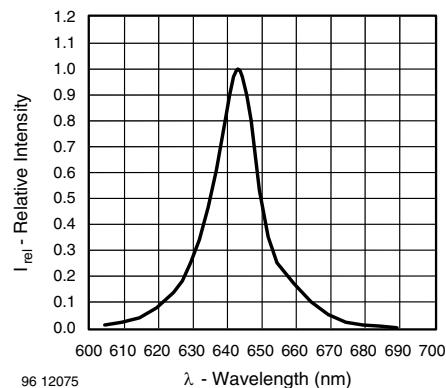
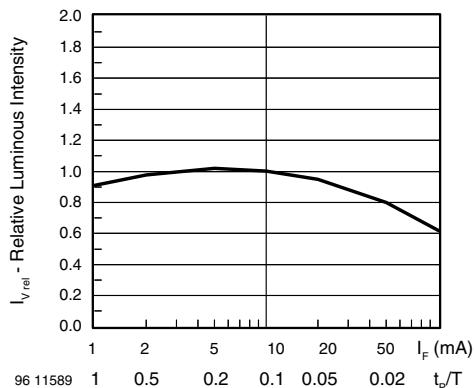
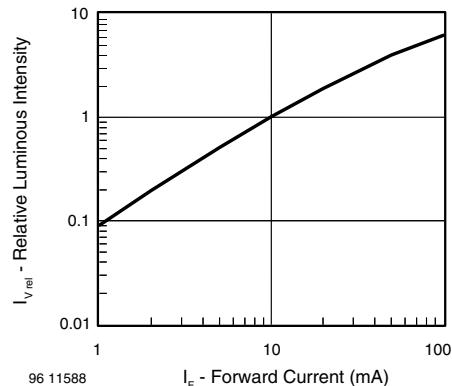
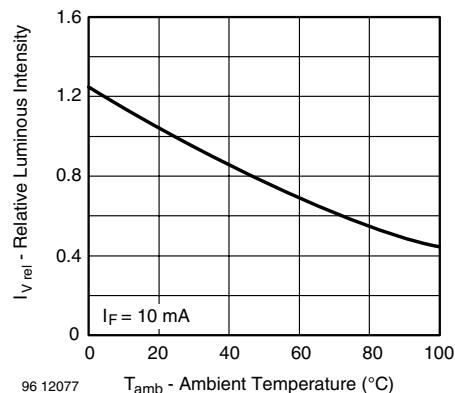
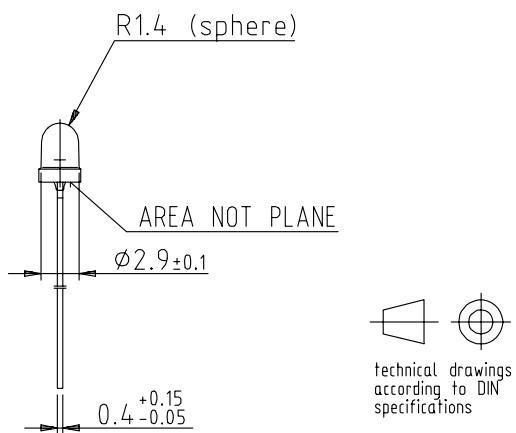
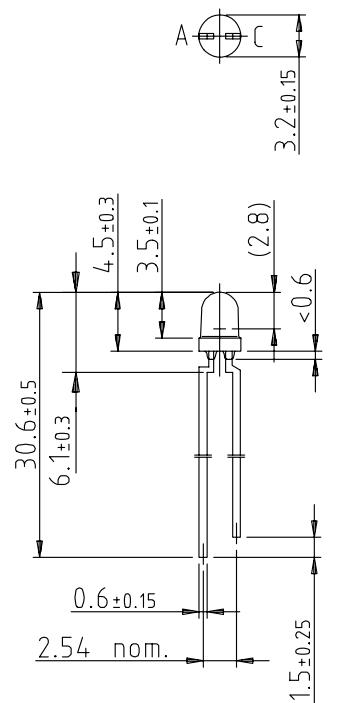


Figure 4. Forward Current vs. Forward Voltage



## PACKAGE DIMENSIONS in millimeters



**Ozone Depleting Substances Policy Statement**

It is the policy of Vishay Semiconductor GmbH to

1. Meet all present and future national and international statutory requirements.
2. Regularly and continuously improve the performance of our products, processes, distribution and operating systems with respect to their impact on the health and safety of our employees and the public, as well as their impact on the environment.

It is particular concern to control or eliminate releases of those substances into the atmosphere which are known as ozone depleting substances (ODSs).

The Montreal Protocol (1987) and its London Amendments (1990) intend to severely restrict the use of ODSs and forbid their use within the next ten years. Various national and international initiatives are pressing for an earlier ban on these substances.

Vishay Semiconductor GmbH has been able to use its policy of continuous improvements to eliminate the use of ODSs listed in the following documents.

1. Annex A, B and list of transitional substances of the Montreal Protocol and the London Amendments respectively
2. Class I and II ozone depleting substances in the Clean Air Act Amendments of 1990 by the Environmental Protection Agency (EPA) in the USA
3. Council Decision 88/540/EEC and 91/690/EEC Annex A, B and C (transitional substances) respectively.

Vishay Semiconductor GmbH can certify that our semiconductors are not manufactured with ozone depleting substances and do not contain such substances.

We reserve the right to make changes to improve technical design  
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